Board shall be fabricated to Performance Class II as per IPC-6011 & IPC-6012
Material: Per IPC-4101A/24/26/29/99, Copper Clad,
High Temperature FR4 Class Epoxy Glass Rated UL94V-0,
0.02 Copper for External Layers & 0.02 Copper for Internal Layers.
Must be RoHS compliant & survive a Lead-Free Assembly Max reflow of 260 DEG C (6 Passes)
T_d Rating: >340 DEG C
Z Axis CTE < 3.5%
T_g > 170 DEG C <Mn>

Solder Mask: SMDBC Per IPC-SM-840C, Class T, Must be RoHS Compliant
TYP LPI, 0.0002 Mn to 0.0008 Max measured over copper plating,
must clear all lands as indicated on gerber solder mask layers, (Color = Red)
Finish: Electro-less Nickel Immersion Gold (ENIG), 2"8 Micro Inches Gold Over 150-250 Micro Inches Nickel
This Assembly shall be RoHS Compliant. Vendor shall deliver assembly with accompanying certificate of compliance.